

ADHESIVES

A COMPREHENSIVE RANGE OF ADHESIVES FOR ELECTRONIC, AUTOMOTIVE AND GENERAL MANUFACTURING INDUSTRIES.

CONSUMABLES

ASSEMBLY MATERIALS AND MACHINE CONSUMABLES USED IN SEMICONDUCTOR, PHOTONIC AND HYBRID ASSEMBLY ETC.

EQUIPMENT

ASSEMBLY, TEST AND INSPECTION EQUIPMENT FOR THE MICROELECTRONIC, ELECTRONIC, PHOTONIC AND SEMICONDUCTOR INDUSTRIES.



Inseto

ADVANCED TECHNOLOGY FOR RESEARCH & INDUSTRY

CONNECT NEWSLETTER

Welcome to the nineteenth issue of our Company Newsletter "Inseto Connect", dedicated to providing information on new products, supplier & company news and technical announcements.

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Thank You!

Inseto is pleased to confirm our nominated Charity for 2016 is once again the Brain Tumour Trust.

First selected in 2011, donations to the Charity via the fund raising group "The Brains Unite Fund" have now exceeded £25,000 following fantastic support from the Company, our employees, suppliers & customers.

We would like to say a big THANK-YOU to all those that have supported us in raising money for this excellent cause! If you would like to find out more, or make a donation, please visit:

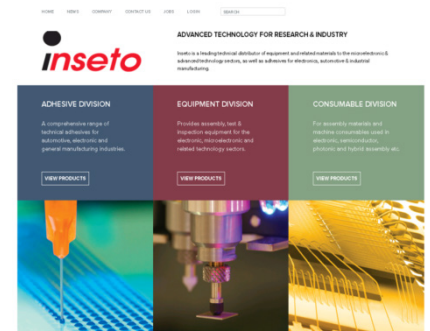
<https://www.thebraintumourcharity.org/get-involved/supporter-groups/groups/the-brains-unite-fund/>

Mobile Friendly Website

We are pleased to announce the release of our new mobile friendly website, which has been designed to adapt and run seamlessly across phones, tablets and desktop devices.

The site features improved navigation and search facilities, enhanced product information, plus a new secure customer portal for accessing key documents.

We hope you find the new site interesting and informative.



IMAPS-UK

Inseto have recently provided free tutorials on "Adhesives" and "Wire Bonding" technology at International Microelectronics Assembly & Packaging Society "IMAPS" UK Educational Workshops. Please contact us if you would like copies of the presentations we provided.

In addition, Inseto has confirmed its Corporate Membership of the Society and will be exhibiting at the annual Conference in Edinburgh on 17th March 2016. We look forward to meeting new and existing customers at this excellent event!

Further information: www.imaps.org.uk

300mm Wafer Prober

Inseto has installed multiple 300mm wafer probers from SemiProbe Based on the Probe System for Life (PS4L) model, installations included manual and semi-automatic versions.

A further semi-automatic model will also be delivered shortly to a UK customer with HV test capability.



Service Vacancy

Inseto currently have a vacancy for a Technical Support Engineer to join our growing engineering team.



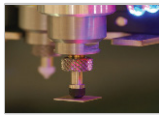
Reporting to the Technical Support Director, the role will entail extensive travel in the UK, Ireland and Scandinavia. Responsibilities include equipment repair, maintenance & calibration, the installation and commissioning of new systems, process support, plus the training of our customers' personnel. Contact us for further details or visit the "Jobs" section on our website.

Bonder Trade-in Offer

Do you presently use an old 41xx series Kulicke & Soffa (K&S) manual wire bonder?



If so, Inseto is presently offering significant trade-in discounts to allow users to bring their equipment up to the latest generation model. Please contact us with details of your bonder for further details.



Equipment News

New Bond Tester from Nordson-DAGE



The 4800 has been developed to address the specific needs of wafer bond testing of up to 450mm wafers, including high-speed X-Y stages, manual-auto wafer handling, warped and thin wafer capability, vision systems, through precision & multi-function cartridges for hot-bump, shear & pull test capability etc.

New Plasma Etchers, Asher & Cleaners

Plasma Etch have released the Venus Series of PC controlled bench-top Plasma Cleaning, Etching and Ashing systems.



The new Venus control software enables fully automatic system operation, MFC gas flow control, multiple recipe storage, data logging & trending, events and multi-step sequencing.

Asterion Automatic Wedge Bonder



The new K&S Asterion Automatic Large Area Wedge Bonder is suitable for large wire, fine wire and power ribbon bonding.

The system is built on an enhanced architecture that includes an expanded bond area of 300 x 300mm (optional extended version up to 300 x 800mm), with new robust pattern recognition capabilities and extremely tight process controls.

Together these deliver heightened productivity, bonding quality and reliability. The enlarged bondable area also enhances flexibility and reduces line integration costs.

Low Cost Wafer Dicing System

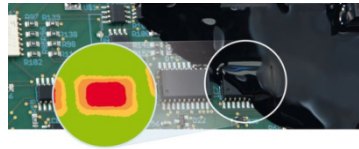
The new 7910 dicing saw from ADT provides a perfect solution for cutting silicon wafers up to 200mm and for dicing or scribing discrete devices etc., in production, development, universities and research facilities.

The systems automatic vision system for full and partial wafers, easy to use Graphic User Interface (GUI) with touch-screen control and single low vibration spindle enabling superb cut quality, all combine to deliver the latest innovations, in an advanced small-footprint system.



Adhesives News

New High Temperature Adhesives



DELO has introduced a range of new epoxies capable of continuously withstanding 250°C. These include a silver-filled version for electrically conductive

applications, an AlN-filled option for thermally conductive, electrically insulating requirements, and an unfilled version for applications such as GlobTop & Dam & Fill. These adhesives show excellent tensile strength even after 500 hours storage at 250°C, and have very high bond strength to materials such as FR4 and PPS when tested at 220°C. With a very low ionic content (<10ppm) and a water absorption rate of 0.1%, these are ideal for microelectronic applications in very harsh environments such as the oil & gas industry.

Dual Curing Adhesives



Dual-curing adhesives are being used more frequently in electronic applications, where positional accuracy is of prime importance and also where low curing temperatures are required. The adhesives fall into three curing categories: individual light and or heat curing; light followed by mandatory heat curing; and light & humidity combinations.



Materials News

OEM Equivalent Welding Electrodes



Advanced Integrated Technologies has been manufacturing precision parallel gap resistance welding electrodes & hot bar reflow solder tools since 1975 & has grown to be the largest manufacturer of these parts worldwide.

Products fit all welding, soldering and bonding equipment including Unitek, Miyachi, MacGregor, Hughes, Palomar and Avio etc.

Download the new OEM equivalent catalogue from the Inseto website.

See us at the following events in 2016:

- MicroTech, 17 March, Edinburgh
- IMAPS-Nordic Conference, 05-07 June, Norway
- European Microwave Week, 03-07 October, London

Contact Information:

Inseto (UK) Limited,
Unit 25 Focus Way, Andover, SP10 5NY
United Kingdom

Tel: +44 (0)1264 334505 - Fax: +44 (0)1264 334449
enquiries@inseto.co.uk - www.inseto.co.uk